

**•General Description**

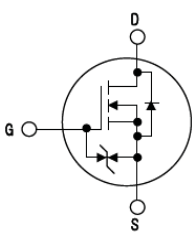
The SJ MOSFET LH65R210 has the low  $R_{DS(on)}$ , low gate charge, fast switching and excellent avalanche characteristics. This device offers extremely fast and robust body diode, and is suitable for telecom and power supplies.

**•Features**

- Extremely Low Switching loss
- Build-in ESD Diode

**•Application**

- LED/LCD/PDP TV and monitor Lighting
- Solar/Renewable/UPS-Micro Inverter System
- Power Supplies

|                                                                                                      |                                                                                                                                    |
|------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------|
|                    | <p><b><math>V_{DS} = 650V</math></b></p> <p><b><math>R_{DS(ON)} = 210m\Omega</math></b></p> <p><b><math>I_D = 16.8A</math></b></p> |
| <br><b>TO-220F</b> | <br><b>TO-220</b>                               |

**■ RoHS COMPLIANT**

**•Ordering Information:**

|                                       |                        |                       |
|---------------------------------------|------------------------|-----------------------|
| Part number                           | LH65R210               | LH65R210              |
| Package                               | TO-220F                | TO-220                |
| Basic ordering unit (pcs)             | 1000                   | 1000                  |
| Normal Package Material Ordering Code | LH65R210F-TO220F-TU    | LH65R210T-TO220-TU    |
| Halogen Free Ordering Code            | LH65R210F-TO220F-TU-HF | LH65R210T-TO220-TU-HF |

**•Absolute Maximum Ratings (TC =25°C)**

| PARAMETER                                                             |            | SYMBOL                | Value                    | UNIT |
|-----------------------------------------------------------------------|------------|-----------------------|--------------------------|------|
| Drain-Source Breakdown Voltage                                        |            | $BV_{DSS}$            | 650                      | V    |
| Gate-Source Voltage                                                   |            | $V_{GS}$              | ±30                      | V    |
| Continuous Drain Current                                              | TC = 25°C  | $I_D$                 | 16.8                     | A    |
|                                                                       | TC = 100°C |                       | 10.6                     |      |
| Pulsed drain current<br>(TC = 25°C, tp limited by Tjmax) <sup>1</sup> |            | $I_{D \text{ pulse}}$ | 50                       | A    |
| Single Pulse Avalanche Energy <sup>1</sup>                            |            | $I_{AR}$              | 2.4                      | A    |
| Single Pulse Avalanche Energy <sup>2</sup>                            |            | $E_{AS}$              | 250                      | mJ   |
| Gate Source ESD(HBM-C=100pF,R=1.5KΩ)                                  |            | $V_{ESD(G-S)}$        | 2000                     | V    |
| Power Dissipation(TC=25°C)                                            |            | $P_D$                 | TO-220:150    TO-220F:33 | W    |
| Operating Temperature and Storage Temperature Range                   |            | $T_J/T_{STG}$         | -55~+150                 | °C   |
| MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 400V$                        |            | dv/dt                 | 50                       | V/ns |
| Reverse diode dv/dt, $V_{DS}=0\ldots 480V, I_{SD} \leq I_D$           |            | dv/dt                 | 15                       | V/ns |

**●Electronic Characteristics**

| PARAMETER                               | SYMBOL       | TEST CONDITION                             | MIN | TYP  | MAX  | UNIT |
|-----------------------------------------|--------------|--------------------------------------------|-----|------|------|------|
| Drain-Source Breakdown Voltage          | $BV_{DSS}$   | $V_{GS}=0V, I_D=250\mu A$                  | 650 | --   | --   | V    |
| Gate Threshold Voltage                  | $V_{GS(TH)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$              | 2.5 | --   | 4.5  | V    |
| Drain-source On Resistance <sup>3</sup> | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=6A$                       | --  | 185  | 210  | mΩ   |
| Drain-Source Leakage Current            | $I_{DSS}$    | $V_{DS}=650V, V_{GS}=0V, T_J=25^\circ C$   | --  | --   | 1    | μA   |
|                                         |              | $V_{DS}=650V, V_{GS}=0V, T_J=125^\circ C$  | --  | --   | 100  |      |
| Gate-Source Leakage Current             | $I_{GSS}$    | $V_{GS}=\pm 20V$                           | --  | --   | ±1   | μA   |
| Forward Transconductance <sup>3</sup>   | $R_G$        | $f=1.0MHz$ open drain                      | --  | --   | 12   | Ω    |
| Input Capacitance                       | $C_{iss}$    | $V_{GS}=0V, V_{DS}=400V, f=1.0MHz$         | --  | 1750 | --   | pF   |
| Output Capacitance                      | $C_{oss}$    |                                            | --  | 39   | --   |      |
| Reverse transfer Capacitance            | $C_{rss}$    |                                            | --  | 3.4  | --   |      |
| Turn-on delay time                      | $T_d(on)$    | $I_D=8.7A, V_{DS}=325V, R_G=25\Omega$      | --  | 39   | --   | nS   |
| Rise time                               | $T_r$        |                                            | --  | 21   | --   |      |
| Turn -Off Delay Time                    | $T_d(off)$   |                                            | --  | 171  | --   |      |
| Fall time                               | $T_f$        |                                            | --  | 18   | --   |      |
| Total Gate Charge                       | $Q_g$        | $I_D=8.7A, V_{DS}=520V, V_{GS}=10V$        | --  | 40   | ---  | nC   |
| Gate-to-Source Charge                   | $Q_{gs}$     |                                            | --  | 8    | --   |      |
| Gate-to-Drain Charge                    | $Q_{gd}$     |                                            | --  | 12   | ---  |      |
| Continuous Diode Forward Current        | $I_S$        |                                            | --  | --   | 16.8 | A    |
| Pulsed Diode Forward Current            | $I_{SM}$     |                                            | --  | --   | 50   | A    |
| Diode Forward Voltage                   | $V_{SD}$     | $T_J=25^\circ C, I_S=8.7A, V_{GS}=0V$      | --  | --   | 1.3  | V    |
| Reverse Recovery Time                   | $t_{rr}$     | $V_{RR}=400V, I_f=I_S, di_f/dt=100A/\mu s$ | --  | 340  | --   | ns   |
| Reverse Recovery Charge                 | $Q_{rr}$     |                                            | --  | 4.7  | --   | μC   |

**●Thermal Characteristics**

| PARAMETER                           | SYMBOL     | MAX     |        | UNIT |
|-------------------------------------|------------|---------|--------|------|
|                                     |            | TO-220F | TO-220 |      |
| Thermal Resistance Junction-case    | $R_{thJC}$ | 3.7     | 0.83   | °C/W |
| Thermal Resistance Junction-ambient | $R_{thJA}$ | 80      | 62     | °C/W |

Notes:

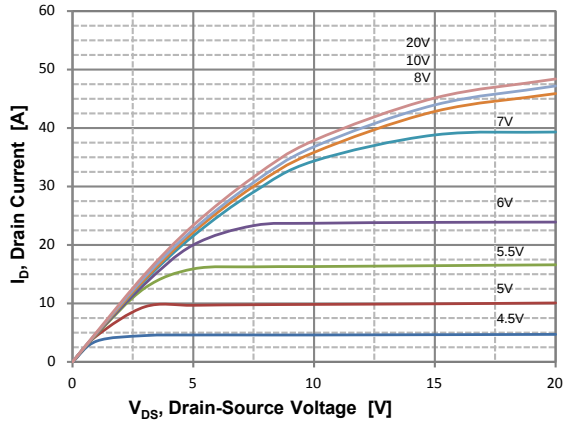
1.Repetitive Rating: Pulse width limited by maximum junction temperature.

2.  $I_{AS} = 2.4A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ C$

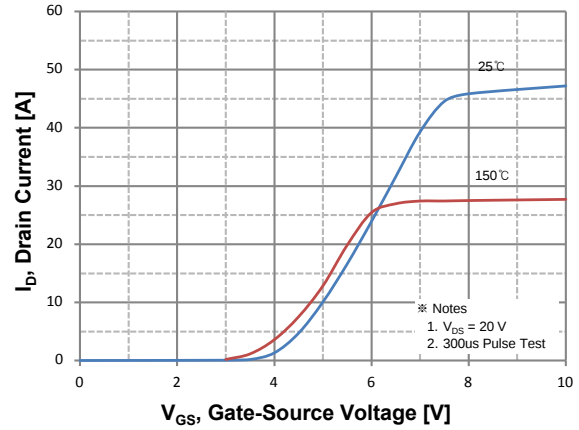
3. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%

• **Typical Characteristics**  $T_J=25^{\circ}\text{C}$ , unless otherwise noted

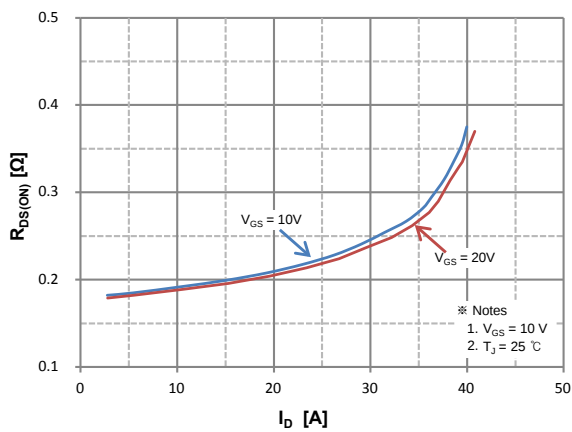
**Figure 1. On Region Characteristics**



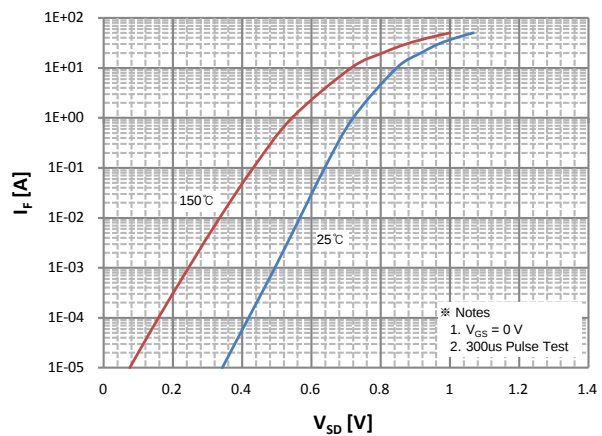
**Figure 2. Transfer Characteristics**



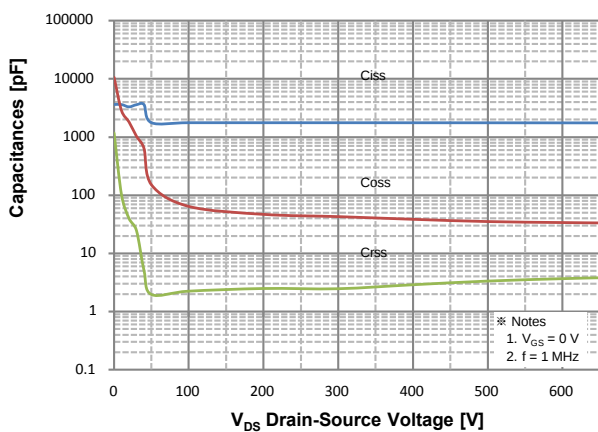
**Figure 3. On Resistance Variation vs Drain Current and Gate Voltage**



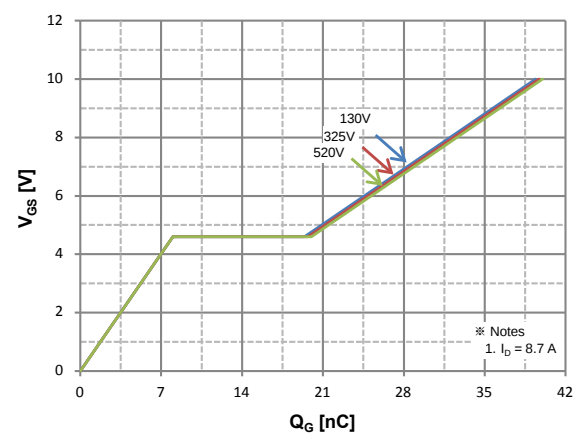
**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

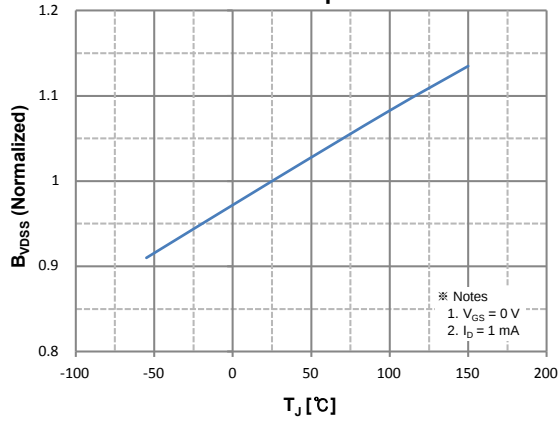


**Figure 6. Gate Charge Characteristics**

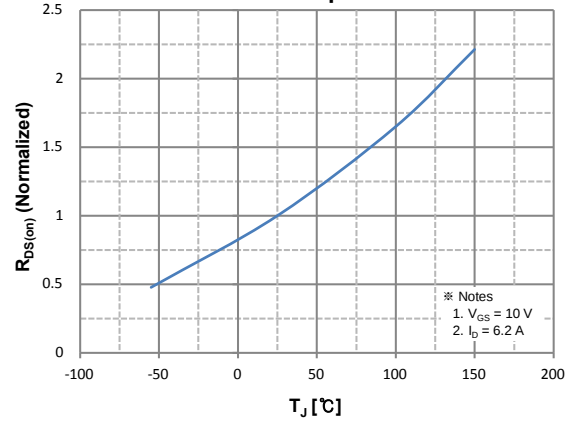


•Typical Characteristics(Cont.)

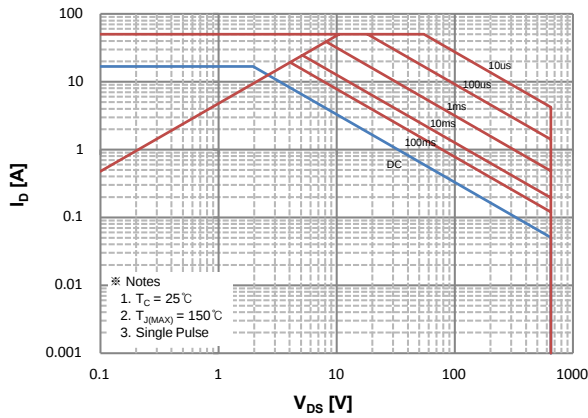
**Figure 7. Breakdown Voltage Variation vs. Temperature**



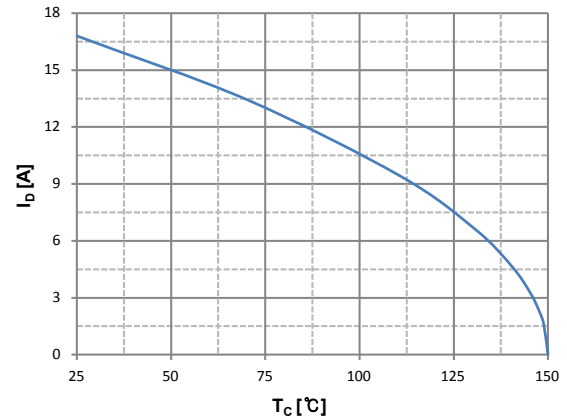
**Figure 8. On-Resistance Variation vs. Temperature**



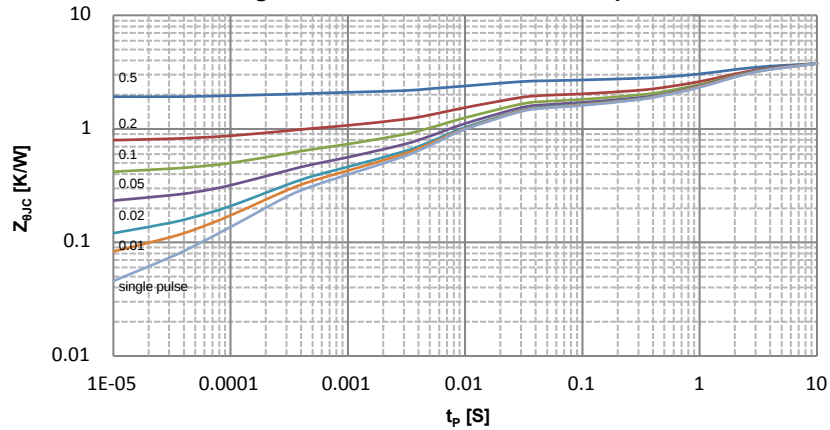
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**



● Test Circuits and Waveforms

Fig 1. Gate Charge Test Circuit & Waveform

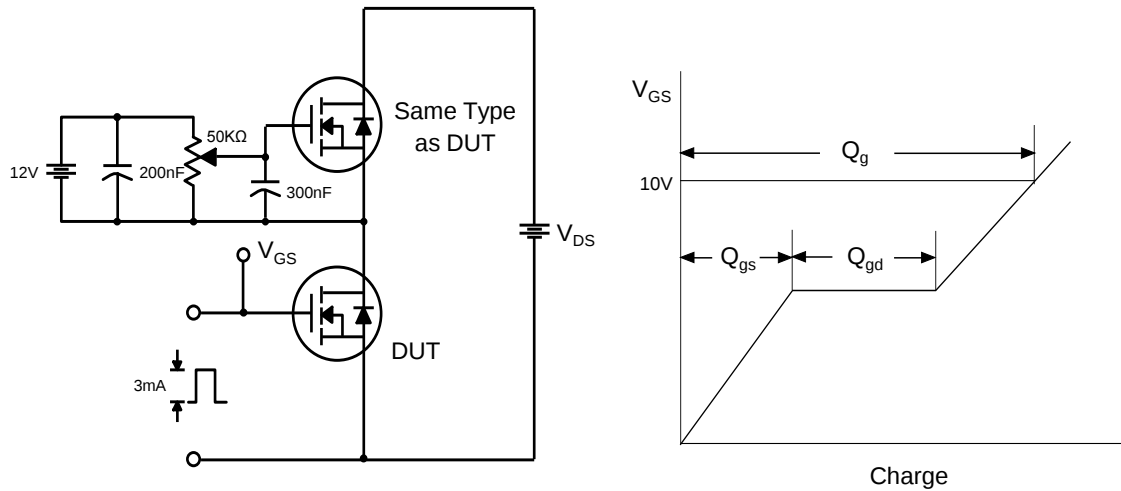


Fig 2. Resistive Switching Test Circuit & Waveforms

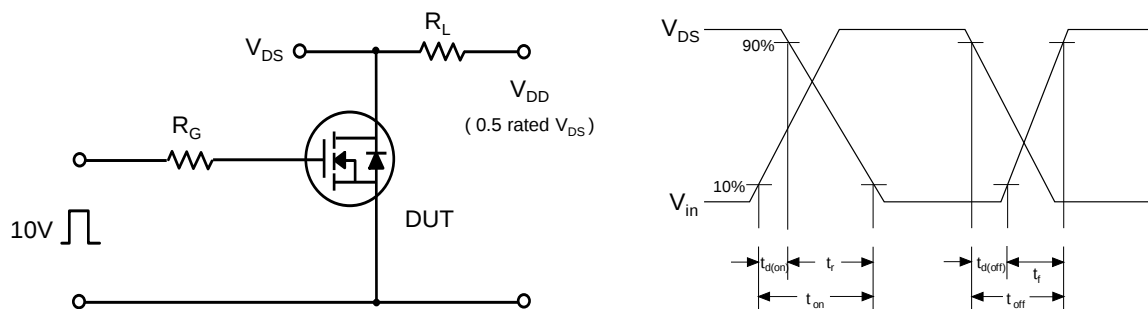
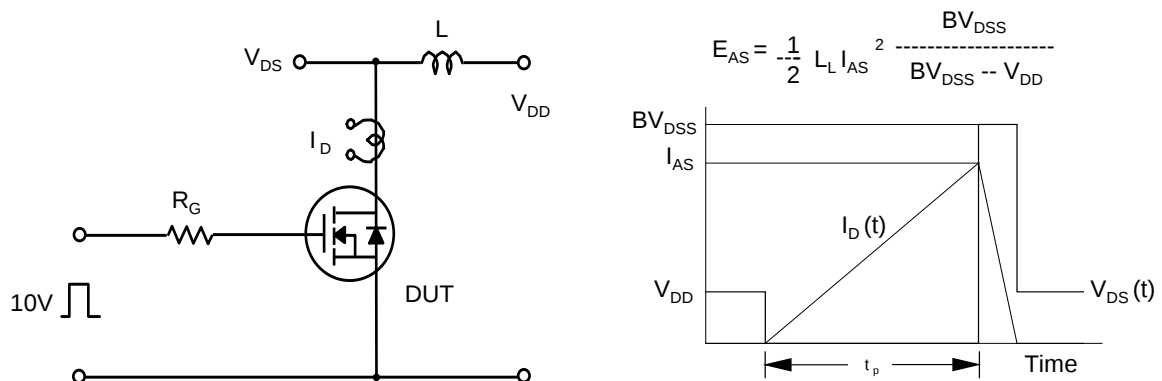
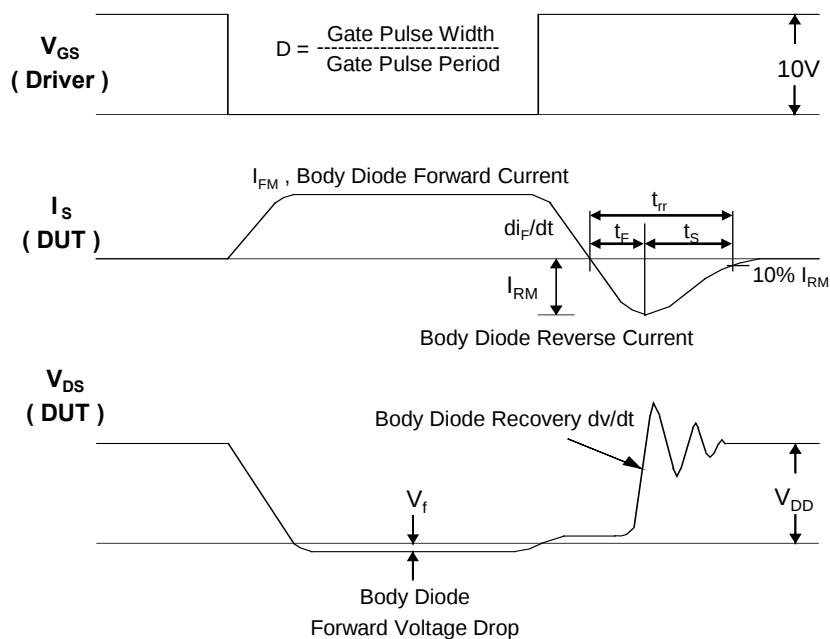
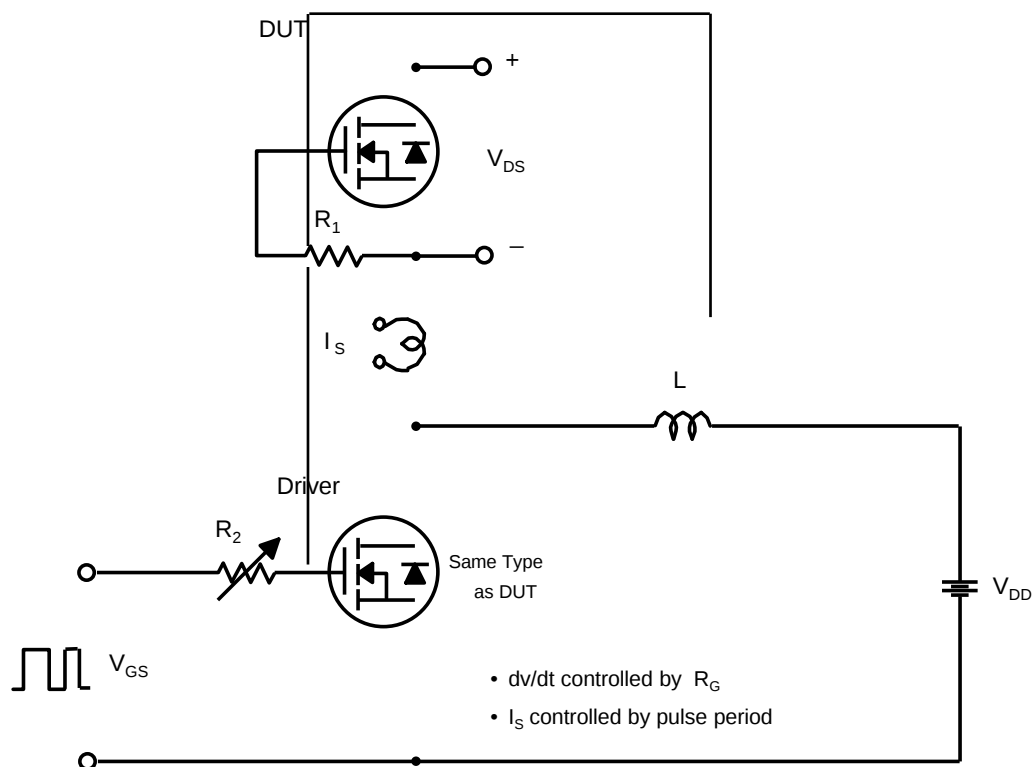


Fig 3. Unclamped Inductive Switching Test Circuit & Waveforms



## ●Test Circuits and Waveforms(cont.)

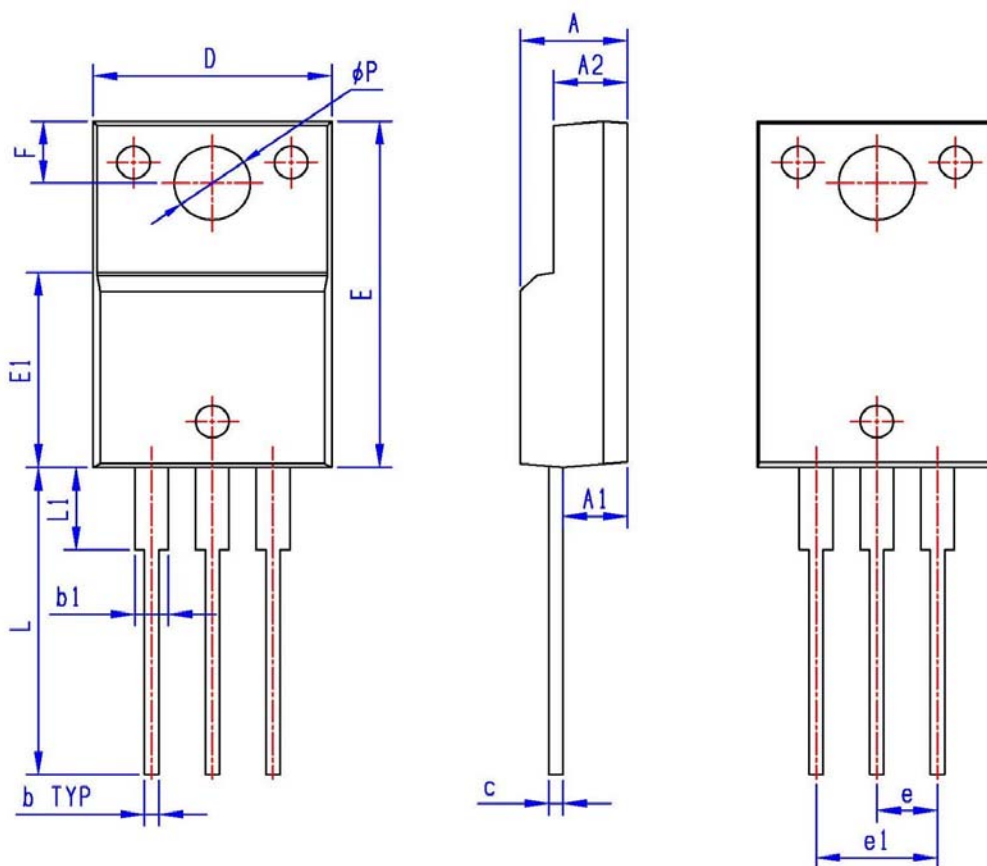
#### Fig 4. Peak Diode Recovery dv/dt Test Circuit & Waveforms



**●Dimensions (TO-220F)**

UNIT:mm

| SYMBOL | min   | max   | SYMBOL | min   | max   |
|--------|-------|-------|--------|-------|-------|
| A      | 4.20  | 4.80  | E1     | 8.30  | 8.70  |
| A1     | 2.50  | 2.90  | e      | 2.40  | 2.70  |
| A2     | 2.90  | 3.30  | e1     | 4.95  | 5.25  |
| b      | 0.40  | 0.80  | F      | 2.50  | 2.90  |
| b1     | 1.10  | 1.50  | L      | 13.00 | 14.00 |
| c      | 0.50  | 0.70  | L1     | 3.00  | 4.00  |
| D      | 9.80  | 10.60 | ∅P     | 2.90  | 3.50  |
| E      | 14.60 | 15.60 |        |       |       |



**●Dimensions (TO-220)**

UNIT:mm

| SYMBOL | min   | max   | SYMBOL | min   | max   |
|--------|-------|-------|--------|-------|-------|
| A      | 4.25  | 4.85  | B1     | 2.60  | 3.00  |
| A1     | 2.30  | 3.00  | e      | 2.40  | 2.70  |
| A2     | 1.20  | 1.40  | e1     | 4.95  | 5.25  |
| b      | 0.60  | 0.90  | L      | 12.60 | 14.40 |
| b1     | 1.10  | 1.70  | L1     | 2.40  | 4.00  |
| c      | 0.40  | 0.70  | ∅P     | 3.50  | 3.90  |
| D      | 9.80  | 10.60 |        |       |       |
| B      | 15.20 | 16.20 |        |       |       |

